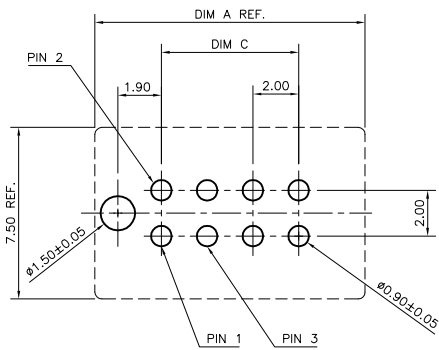
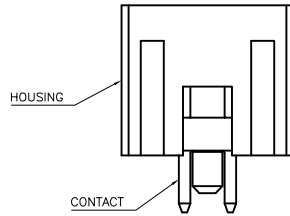
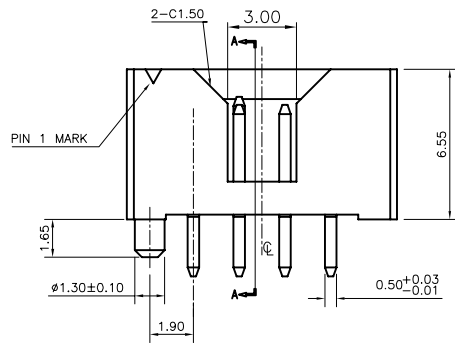
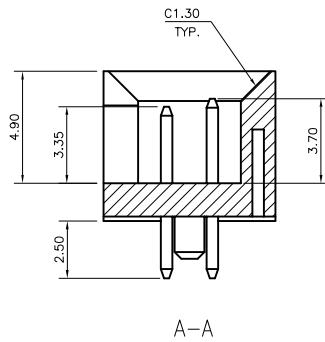


Pin4 為長pin; Other pin 為短pin



RECOMMENDED PCB LAYOUT ( TOP VIEW )  
GENERAL TOLERANCE ±0.05



NOTES:

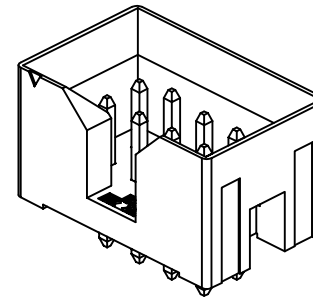
- MATERIAL:
  - HOUSING: THERMOPLASTIC, HIGH TEMP. (PA4T), UL94V-0;
  - CONTACT: COPPER ALLOY
- CONTACT:
  - 50u" MIN. NICKEL UNDER PLATING OVERALL.
  - 1: GOLD FLASH PLATING.
  - C: 15u" GOLD PLATING ON CONTACT AREA.
  - D: 30u" GOLD PLATING ON CONTACT AREA.
  - N: 80u" MIN MATTE TIN PLATING.
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-51455-xxxx-xxx
- PACKAGE PLS REFER TO 51455-xxxx-xx-TRP
- PART NUMBER

51455-XXX X X-XXX

NO OF CKT	XXX	HOUSING COLOR	PACKAGE
PACKING	001	BLACK	51455-XXXCR-00
0: TAPE & REEL	002	BLACK	51455-XXXCR-05

PLATING

- GOLD FLASH
- 15u" GOLD PLATING ON CONTACT AREA.
- 30u" GOLD PLATING ON CONTACT AREA.
- 80u" MIN MATTE TIN PLATING.



CKT.	DIM A	DIM B	DIM C
006	9.8	6.7	4.0
008	11.8	8.7	6.0

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ	DRAWN BY Zhu, Wei DATE 20/11/16	
GENERAL TOLERANCES (UNLESS SPECIFIED)	CHECKED BY Xu, Zhi Yong DATE 20/11/16	
X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY Xu, Zhi Yong DATE 20/11/16	TITLE 2.0mm Pitch WTB Wafer Conn. T/H D/R S/T Type
	UNITS mm	SIZE A4
	SCALE 4:1	DWG NO. 51455-XXXXX-XXX
	SHEET NO. 1 OF 1	REV B
		PART NO. SEE NOTES